



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
			<i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-26
Contact Name *	Refer to Supplier Comment section		
Authorized Representative *	Patrick Crudo	Representative Title	MMS MD CHAMPION
Representative Phone *	(+33) 442 688 339	Representative Email *	patrick.crudo@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L011E4Y6TR	H095*457CCCZ	A	9989	2017-01-26
Amount	UoM	Unit type	ST ECOPACK Grade	
5.072	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information					
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented		
1	260	3			
bulk Solder Termination	Terminal Plating	Terminal Base Alloy			Comment
SACN125	NAC	Copper Alloy			

Package Designator	Size	Nbr of instances	Shape
WLCSF	2.133x2.07x0.555	25	flat
Comment	Package : A05M WLCSF 25L DIE 457 P 0.4 DM00158954		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	H095*457CCCZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.686	mg	supplier	die	Silicon (Si)	7440-21-3		3.559	mg	965545	701763
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	2984	2169
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.037	mg	10038	7296
Die				supplier	metallization	Tantalum (Ta)	7440-25-7		0.004	mg	1085	789
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	1628	1183
Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.010	mg	2713	1972
Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.059	mg	16007	11634
Coating-P11-HD4100_Hitachi Chemical	Other organic materials	0.025	mg	Supplier	Plastics/polymers	PD-9 Resin	Proprietary		0.017	mg	679612	3339
Coating-P11-HD4100_Hitachi Chemical				Supplier	Plastics/polymers	Trifluoroacetic Anhydride	407-25-0		0.001	mg	58252	286
Coating-P11-HD4100_Hitachi Chemical				Supplier	Plastics/polymers	Tetraethylene Glycol Dimethacrylate	109-17-1		0.004	mg	145631	715
Coating-P11-HD4100_Hitachi Chemical				Supplier	Plastics/polymers	4,4'-Oxydipthalic Anhydride	1823-59-2		0.001	mg	58252	286
Coating-P11-HD4100_Hitachi Chemical				Supplier	Plastics/polymers	2-Hydroxyethyl Methacrylate	868-77-9		0.001	mg	58252	286
Coating-P12-HD4100_Hitachi Chemical	Other organic materials	0.037	mg	Supplier	Plastics/polymers	PD-9 Resin	Proprietary		0.025	mg	679612	5008
Coating-P12-HD4100_Hitachi Chemical				Supplier	Plastics/polymers	Trifluoroacetic Anhydride	407-25-0		0.002	mg	58252	429
Coating-P12-HD4100_Hitachi Chemical				Supplier	Plastics/polymers	Tetraethylene Glycol Dimethacrylate	109-17-1		0.005	mg	145631	1073
Coating-P12-HD4100_Hitachi Chemical				Supplier	Plastics/polymers	4,4'-Oxydipthalic Anhydride	1823-59-2		0.002	mg	58252	429
Coating-P12-HD4100_Hitachi Chemical				Supplier	Plastics/polymers	2-Hydroxyethyl Methacrylate	868-77-9		0.002	mg	58252	429
RDL-Ti Target_Materion	Other inorganic materials	0.001	mg	Supplier	Metals	Titanium	7440-32-6		0.001	mg	1000000	159
RDL-Cu Target_Materion		0.003	mg	Supplier	Metals	Copper	7440-50-8		0.003	mg	1000000	629
RDL-Cu Anode_Lam Research		0.064	mg	Supplier	Metals	Copper	7440-50-8		0.064	mg	1000000	12586
UBM-Ti Target_Materion	Other inorganic materials	0.000	mg	Supplier	Metals	Titanium	7440-32-6		0.000	mg	1000000	85
UBM-Cu Target_Materion		0.002	mg	Supplier	Metals	Copper	7440-50-8		0.002	mg	1000000	334
UBM-Cu Anode_Lam Research		0.073	mg	Supplier	Metals	Copper	7440-50-8		0.073	mg	1000000	14377
Solder Ball-SACN125_Senju	Solder	1.180	mg	Supplier	Metals	Tin	7440-31-5		1.160	mg	982500	228631
Solder Ball-SACN125_Senju				Supplier	Metals	Silver	7440-22-4		0.014	mg	12000	2792
Solder Ball-SACN125_Senju				Supplier	Metals	Copper	7440-50-8		0.006	mg	5000	1164
Solder Ball-SACN125_Senju				Supplier	Metals	Nickel	7440-02-0		0.001	mg	500	116